

Description

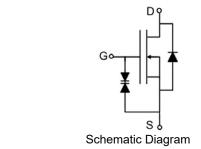
Features

- 600V, 0.03A
 - $R_{DS(ON)}$ < 700 Ω @ V_{GS} =0V
 - $R_{DS(ON)}$ < 8000 @ V_{GS} = 10V
- Self-aligned planner technology
- Pb-free lead plating
- Halogen free
- ESD improved capability

Application

- Load Switch
- PWM Application
- Power management





Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
VSM501A-S2	VSM501A	TAPING	SOT-23-3	7inch	3000	180000

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter	Max.	Units	
V_{DSS}	Drain-Source Voltage	600	V	
V _{GSS}	Gate-Source Voltage	±20	V	
	Continuous Drain Current	T _A = 25°C	0.03	Α
l _D		T _A = 100°C	0.02	Α
I _{DM}	Pulsed Drain Current note1	0.12	Α	
dv/dt	Peak Diode Recovery dv/dt	5.0	V/ns	
V _{ESD(G-S)}	Gate source ESD (HBM-C= 100pF, R=1.5kΩ)	300	V	
P _D	Power Dissipation	T _A = 25℃	0.5	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	250	°C/W	
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	$^{\circ}\!\mathbb{C}$	



Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	cteristic				•	
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = -5V, I _D =250μA	600	-	-	V
I _{D(off)}		V _{DS} =600V, V _{GS} = -5V, T _J =25°C	-	-	0.1	μA
	Off-state Drain to Source Current	V _{DS} =480V, V _{GS} =-5V, T _J =125°C	-	-	10	μA
I _{GSS}	Gate to Source Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Charac	cteristics	•				
I _{DSS}	On-state drain current	V _{GS} =0V, V _{DS} =25V	12	_	_	mA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =3V, I _D =8µA	-2.7	-1.8	-1.0	V
	Static Drain-Source on-Resistance	V _{GS} =0V, I _D =3mA	-	350	700	Ω
$R_{DS(on)}$	note2	V _{GS} =10V, I _D =16mA	-	400	800	
Dynamic C	Characteristics	•				
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =-5V, f = 1.0MHz	-	50	-	pF
Coss	Output Capacitance		-	4.53	-	pF
C_{rss}	Reverse Transfer Capacitance		-	1.08	-	pF
Qg	Total Gate Charge	., ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	-	1.14	-	nC
Q _{gs}	Gate-Source Charge	$V_{DS} = 400V$, $I_D = 0.01A$, $V_{GS} = -5V$ to $5V$	-	0.5	-	nC
Q_{gd}	Gate-Drain("Miller") Charge	VGS 3V 10 3V	-	0.37	-	nC
Switching	Characteristics	•				
t _{d(on)}	Turn-on Delay Time	.,	-	9.9	-	ns
t _r	Turn-on Rise Time	V _{DS} =300V,	-	55.8	-	ns
t _{d(off)}	Turn-off Delay Time	$I_D=0.01A, R_{GEN}=6\Omega,$	-	56.4	-	ns
t _f	Turn-off Fall Time	V_{GS} =-5V to 7V	-	136	-	ns
Drain-Sou	rce Diode Characteristics and Maxim	num Ratings				
Maximum Continuous Drain to Source Diode		e Diode Forward			0.00	_
ls	Current			-	0.03	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	0.12	Α
V _{SD}	Diode Forward Voltage	I _F =16mA, VGS=-5V	•	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} =-5V, I _F =0.01A,	•	243	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/µs	-	636	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



Figure1: Output Characteristics

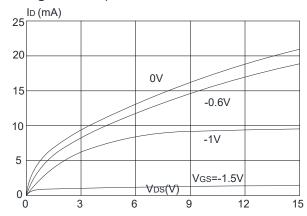


Figure 3:On-resistance vs. Drain Current

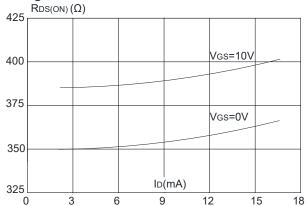


Figure 5: Gate Charge Characteristics

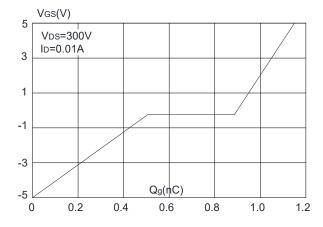


Figure 2: Typical Transfer Characteristics

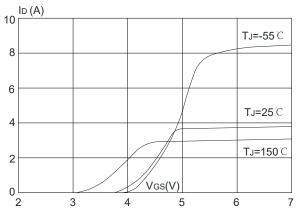


Figure 4: Body Diode Characteristics

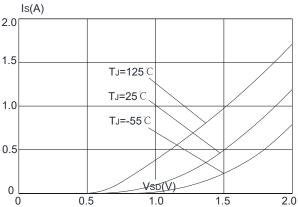


Figure 6: Capacitance Characteristics

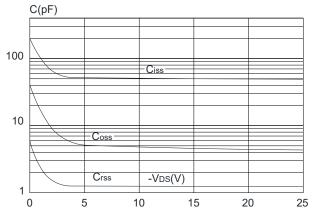




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

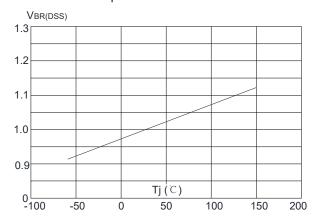


Figure 9: Maximum Safe Operating Area

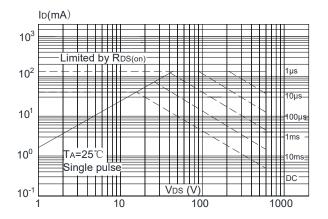


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

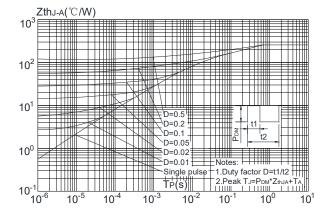


Figure 8: Normalized on Resistance vs. Junction Temperature

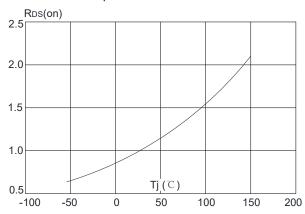
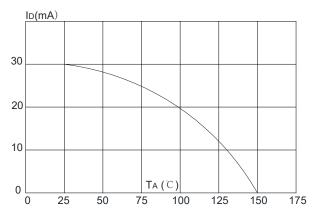


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature





Test Circuit

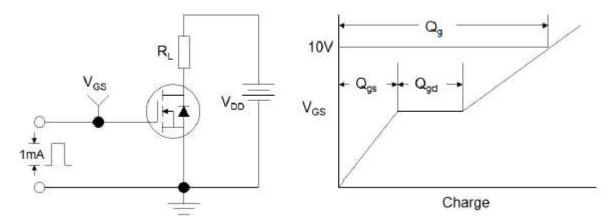


Figure1:Gate Charge Test Circuit & Waveform

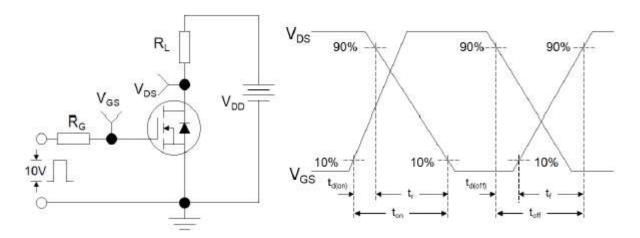


Figure 2: Resistive Switching Test Circuit & Waveforms

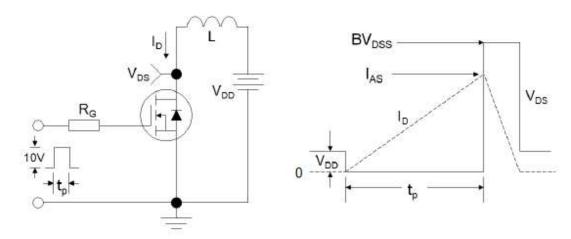


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms